

A B S T R A C T

Communication reliability between a probe electrode and a pad electrode is suppressed from being degraded.

A storage system according to one embodiment  
5 includes: a wafer including a memory chip unit including a  
pad electrode including a first portion and a second  
portion electrically coupled to each other, and a memory  
cell array electrically coupled to the pad electrode; and  
a prober that is able to hold the wafer and executes  
10 reading and writing on the memory cell array. The prober  
includes a probe card including a probe electrode that is  
able to be in contact with the pad electrode, and a memory  
controller that is able to execute reading and writing on  
the memory cell array via the probe electrode, and a  
15 movement mechanism that moves the probe card or the held  
wafer to bring the pad electrode of the held wafer into  
contact with the probe electrode. The movement mechanism  
executes a first operation that brings the probe electrode  
into contact with the first portion of the pad electrode  
20 and does not bring the probe electrode into contact with  
the second portion, and a second operation that does not  
bring the probe electrode into contact with the first  
portion of the pad electrode and brings the probe  
electrode into contact with the second portion.